



Media Release

UTAC Bolsters QFN Package Portfolio

Launches 0.3mm thin QFN package and side lead plated solutions

Singapore, 6 April 2015 – UTAC Holdings Ltd (UTAC), a Singapore-based semiconductor testing and assembly services provider, has introduced two new offerings to bolster its quad flat no-lead (QFN) portfolio (see appendix) - a 0.3mm thin QFN package and a side lead plating (SLP) process that improves QFN solder joints for automotive, aerospace and other harsh environmental applications. Both offerings are qualified with major customers and scheduled to go into mass production in the second half of 2015.

This latest member of UTAC's thin QFN portfolio will allow customers to meet increasing market demand for slimmer, lighter products, such as smartphones, smart watches, fitness bands, and smart cards; while retaining the same QFN product features of low power, high performance and value.

UTAC has been qualified by major automotive customers for its QFN side lead plated solutions, also termed a wettable flank solution, which improves QFN solder joints for improved printed circuit board assembly throughput and solder joint reliability. This solution is commonly used for a wide range of automotive devices, such as airbags, car distance sensors, and rear view mirror camera processors.

"We believe QFN packages will be one of the fastest growing package types in the industry fueled by proliferation of Internet of Things (IoT) devices with increasing usage of sensors, microcontrollers and communication chips in smart devices and automotive. With UTAC's broad QFN portfolio and ability to provide full-turnkey services, we are well positioned to support this growth and deliver market-relevant QFN solutions to meet the needs of our customers," said Mr Asif Chowdhury, UTAC Senior Vice President of Product Line & Marketing.

– End –

Please visit http://www.utacgroup.com/technology_portfolio.html for more information on UTAC's QFN Portfolio.

APPENDIX

Figure 1: QFN Package Portfolio and Applications

Packages	Applications
<p>Thin QFN Thickness range: ≤ 0.4 mm</p>  <p>Thickness 0.85 mm.</p> <p>Thickness ≤ 0.40 mm.</p> <p>Illustration of thin QFN versus other QFN packages</p>	 <p>Smart Card</p>  <p>Smart Watch/Fitness Band</p>  <p>Smartphone/Tablet</p>  <p>Smart TV</p>
<p>QFN Package size range: 0.6x1.0 to 14x14 mm Package thickness range: 1.0 to 0.3 mm</p> 	
<p>GQFN Package size range: 2x2 to 10x10 mm</p> 	
<p>Side Lead Plated QFN Package size range: 2x2 to 10x10 mm</p> 	<p><u>Automotive</u></p>  <p>Infotainment</p>  <p>Airbags</p>  <p>Rear View Mirror Camera</p>

About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of semiconductor assembly and testing services for a broad range of integrated circuits including analog, mixed-signal & logic and memory. The Company offers a full range of package and test development, engineering and manufacturing services and solutions to a worldwide customer base, comprising integrated device manufacturers (IDMs), fabless companies and wafer foundries. UTAC operates manufacturing facilities in Singapore, Thailand, Taiwan, Malaysia, Indonesia and China, in addition to its global network of sales offices in the United States, Europe, Japan, Korea, China and Singapore.

For more information, please visit www.utacgroup.com or contact:

Roger NG

Director, Investor Relations and Communications
DID: (65) 6714 2245; HP: (65) 9005 0132
Email: roger_ng@utacgroup.com

Sherena LIEW

Manager, Communications
DID: (65) 6714 2280; HP: (65) 9742 1436
Email: sherena_liewls@utacgroup.com